

Title (en)
COPPER-TIN ALLOY PLATING BATH

Title (de)
KUPFER-ZINN-LEGIERUNGSPLOTTIERUNGSBAD

Title (fr)
BAIN DE PLACAGE D'ALLIAGE DE CUIVRE-ÉTAIN

Publication
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Application
EP 15829133 A 20150728

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Abstract (en)
[origin: EP3178969A1] An object of this invention is to provide a copper-tin alloy plating bath that allows for film thickening without using cyanide ions, and that can also be applied to barrel plating. This invention relates to a copper-tin alloy plating bath comprising an aqueous solution containing a water-soluble copper compound, a water-soluble divalent tin compound, a sulfur-containing compound represented by formula (1): $\text{R}-(\text{CH}_2)_1-\text{S}-(\text{CH}_2)_m-\text{S}-(\text{CH}_2)_n-\text{R}$ (1), wherein R is H, OH, or SO_3Na , and 1, m, and n are each independently an integer of 0 to 3, and a hydroxyl group-containing aromatic compound.

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